



BRFS Reliability Test results

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OS Design DEPT.3

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No.	Test Item	Testing conditions	Conditions of acceptability	Number of samples	Number of failures
1	Heat cycle test	(1) -40°C~125°C 30minutes each (2) 800cycles	(1)No degradation of electric characteristics after test.	5	0
2	High temperature/ High humidity bias test	(1) Ta=85°C,RH=85% (2) At rated input (3) Load 0% (4) 1000hours	(1)No degradation of electric characteristics after test.	5	0
3	Soldering heat test	(1) 260°C,15seconds (2) Mounting board : t=1.6mm / FR-4	(1)No crack at solder joint. (2)No marked damage of appearance.	1	0
4	Soldering test	(1) Pre-process Vapor agein(100°C/100%),1H Flux treatment (2) Soldering 235°C±5°C,2seconds	(1)Over 95% of dipped part is covered with solder.	1	0
5	Pin strength test immunity test	(1) Weight : 2kg (2) Bending angle:90 deg., total 180 deg. (3) 1 cycle	(1)No degradation of electric characteristics after test. (2)No broken or bent pin.	5	0